

# **2006 Conference on High Density Microsystem Design and Packaging and Component Failure Analysis**

**Shanghai, China  
27 – 30 June 2006**



**IEEE Catalog Number:**  
**ISBN:**

**06EX1427**  
**1-4244-0488-6**

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**IEEE Catalog Number:** 06EX1427

**ISBN:** 1-4244-0488-6

**Library of Congress Number:** 2006926703

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